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Wood et al.

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[54] **METHOD FOR MAKING A WAFER-PAIR  
HAVING SEALED CHAMBERS**[75] Inventors: R. Andrew Wood, Bloomington;  
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216/33; 216/39; 216/56; 438/54; 438/456;  
438/700; 438/703[58] Field of Search ..... 216/2, 24, 33,  
216/39, 56; 438/54, 456, 700, 703[56] **References Cited****U.S. PATENT DOCUMENTS**

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5,851,631 12/1998 Borden et al. .... 428/156*Primary Examiner*—Nam Nguyen  
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*Attorney, Agent, or Firm*—John G. Shudy, Jr.[57] **ABSTRACT**

A method for fabricating a wafer-pair having at least one recess in one wafer and the recess formed into a chamber with the attaching of the other wafer which has a port plugged with a deposited layer on its external surface. The deposition of the layer may be performed in a very low pressure environment, thus assuring the same kind of environment in the sealed chamber. The chamber may enclose at least one device such as a thermoelectric sensor, bolometer, emitter or other kind of device. The wafer-pair typically will have numerous chambers, with devices, respectively, and may be divided into a multiplicity of chips.

**24 Claims, 4 Drawing Sheets**